Intel® Server Board S2600KP Product Family

Efficient, high-density solution with optimized memory performance for preferred value in high performance computing (HPC) deployments



The Intel® Server Board S2600KP is specifically designed for optimal memory performance in the HPC market. It features support for dual Intel® Xeon® processors E5–2600 v3, with 8 DIMM's (1DPC) and optional onboard FDR Infiniband*.

Customizable as a 2U, four node system, it features easy serviceability and high availability with hot-swappable compute modules, 2.5" or 3.5" drive bays, and redundant power supply modules plus better I/O flexibility via support for Intel® I/O Modules, and an onboard dedicated management port.





Target ApplicationsHigh Performance Computing,
Data Analytics

INTEL® SERVER BOARD S2600KP PRODUCT FAMILY			
FEATURES	BENEFITS		
Dual Intel® Xeon® processor E5-2600 v3 product family, 145W max TDP, 160 W for board only	Fits up to 4 boards (8 sockets) in a 2U rack chassis for highly demanding distributed processing and intensive application workloads		
Maximum TDP processor support for 3rd party solutions with custom water cooling design	Enables efficient computing performance		
8 DDR4 DIMM slots (1DPC), up to 128GB per DIMM, 1.0 TB total memory	Memory bandwidth and capacity optimized for performance		
3 risers, 64 I/O lanes available on the board, Connect IB FDR Infiniband* onboard option	High I/O capacity in a dense form factor board		

Technical Information		
Description	A high density, half width form factor with dual Intel® Xeon® processors E5-2600 v3 support and 8 DIMMs per server board designed for efficient HPC environments	
Form Factor	Board: custom (6.4" x 17.7")	
	2U rack: 3.5" drive model (17.24" x 30.35" x 3.42") 2.5" drive model (17.24" x 28.86" x 3.42")	
Compute Module Supported Each chassis will support up to 4 compute modules	HNS2600KPR: 8 DIMM slots, 2 x 1GbE (RJ45)	
	HNS2600KPFR: 8 DIMM slots, InfiniBand* FDR (56-Gb/s) , 2 x 1GbE (RJ45)	
Processors Supported	Dual Intel® Xeon® processor E5-2600 v3 product family	
Total Slots	3 Riser slots	
Slot Types	PCI Express * x24 riser super slot, and PCI Express 3.0 x16 riser slot	
Memory Capacity	4×8 DIMM slots supporting ECC DDR4 RDIMM and LRDIMM with 1333MT/s, 1600MT/s, 1866MT/s, and 2133MT/s speeds	
	1 TB max	
Drive Options	16 or 24 x 2.5" or 12 x 3.5" hot-swap drives	
System Cooling	Fixed cooling fans	
Power Supply Options	1600W common redundant power supply (Platinum Efficiency)	
Storage Options Hot-swap Drive Bays	12 x 3.5" 6Gbps SATA drives - or- 12Gbsp SAS drives with optional SAS bridge board 16×2.5 " 6Gbps SATA drives - or- 12Gbsp SAS drives with optional SAS bridge board	

Available SKUs

Intel® Server Board S2600KP Product Family	Intel® Compute Module HNS2600KP Product Family	Intel® Server Chassis H2000G Product Family
S2600KPFR (w/ InfiniBand)	HNS2600KPFR (w/ InfiniBand)	H2312XXKR2
S2600KPR	HNS2600KPR	H2216XXKR2
S2600KPTR (w/ TPM)		

For more information on Intel server solutions visit: intelserveredge.com For more information on Intel server products visit: intel.com/intelserverboards For product specifications visit: ark.intel.com



Product does not include memory, processors, or hard drives. For compatibility information please refer to the configuration guide at www.intel.com/support

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